# Monthly LabAdviser update: 9/5 2014

|  |  |  |
| --- | --- | --- |
| Updated Subject  | Contributor | Link to the updated pages |
| **Clean room phone numbers**Has been added to the front page after a user request | **Berit G. Herstrøm @danchip** | <http://labadviser.danchip.dtu.dk/index.php/LabAdviser#Cleanroom_naming_and_phone_numbers> |
| **Deposition of Germanium in Wordentech**New recipe and results for deposition of Germanium in Wordentech | **Katharina Nilson****@Danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Germanium/Thermal_Ge_deposition_Wordentec> |
| **Stress in Nickel films** New information om stress in nickel films deposited in Wordentech | **Katharina Nilsn****@Danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Nickel/Stress_Wordentec_Ni_films> |
| **PECVD2**Information has been merged on the PECVD page and removed from the III-V entry | **Berit G. Herstrøm @danchip** | [PECVD equipment page](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/PECVD)[Deposition\_of\_Silicon\_Oxide\_using\_PECVD](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Deposition_of_Silicon_Oxide_using_PECVD#Recipes_on_PECVD3_for_deposition_of_silicon_oxides) |
| **Jipelec RTP**The page has been removed from the III-V entry and can now be found in the Thermal process entry | **Mikkel Mar @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/Jipelec_RTP> |
| **Wet III-V etches**The information has been moved to the etch page. | **Karen Birkelund @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Wet_III-V_Etches> |
| **Photolithography entry has been removed**Has been taken over by the lithography entry. If you miss some information you used to find in the old photolithography entry, please let us know. |  |  |
| **LASER machining**-Adding graph for Average output power for 1064nm and 532nm wavelength. - Adding graph for Pulse energy regarding the repetition rate.- Update the “Redeposition of material” section under “Silicon cutting and milling” | **Chantal Silvestre @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Laser_Micromachining_Tool#Performances> click on Output power…” and “Pulse energy”<http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Back-end_processing/Laser_Micromachining_Tool/Silicon_cutting_and_milling> |